2-1658043-3 ACTIVE

MICTOR

TE Internal #: 2-1658043-3

PCB Mount Receptacle, Vertical, Board-to-Board, 120 Position, .8 mm [.031 in] Centerline, Fully Shrouded, Gold Flash, Surface

Mount, Power & Signal

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Connectors > PCB Connectors > PCB Headers & Receptacles



PCB Connector Assembly Type: PCB Mount Receptacle

PCB Mount Orientation: Vertical
Connector System: Board-to-Board

Number of Positions: 120

Centerline (Pitch): .8 mm [.031 in]

Features

Product Type Features

| PCB Connector Assembly Type | PCB Mount Receptacle |
|-----------------------------------|-----------------------|
| Connector System | Board-to-Board |
| Header Type | Fully Shrouded |
| Sealable | No |
| Connector & Contact Terminates To | Printed Circuit Board |

Configuration Features

| Stackable | No |
|----------------------------------|--------------|
| Connector Contact Load Condition | Fully Loaded |
| PCB Mount Orientation | Vertical |
| Number of Positions | 120 |
| Board-to-Board Configuration | Parallel |

Electrical Characteristics

| Dielectric Withstanding Voltage (Max) | 675 VAC |
|---------------------------------------|---------|
| Insulation Resistance | 2 ΜΩ |
| Impedance | 100 Ω |
| Operating Voltage | 125 VAC |

Body Features

| Assembly Process Feature Material | Polyimide Film |
|-----------------------------------|----------------|



| Primary Product Color | Black |
|--|--|
| Contact Features | |
| Mating Tab Width | .38 mm[.015 in] |
| Mating Tab Thickness | .2 mm[.008 in] |
| Contact Shape & Form | Single Beam |
| PCB Contact Termination Area Plating Material | Gold |
| Contact Base Material | Phosphor Bronze |
| Contact Mating Area Plating Material | Gold Flash |
| Contact Mating Area Plating Material Thickness | .12 μm[5 μin] |
| Contact Type | Socket |
| Contact Current Rating (Max) | 1.25 A, 9.5 A |
| Termination Features | |
| Rectangular Termination Post & Tail Thickness | .15 mm[.006 in] |
| Rectangular Termination Post & Tail Width | 1.77 mm[.07 in] |
| Termination Method to Printed Circuit Board | Surface Mount |
| Mechanical Attachment | |
| PCB Mount Alignment Type | Locating Posts |
| Mating Retention | With |
| Mating Alignment | Without |
| PCB Mount Retention | With |
| PCB Mount Alignment | With |
| Connector Mounting Type | Board Mount |
| Housing Features | |
| Centerline (Pitch) | .8 mm[.031 in] |
| Housing Material | LCP (Liquid Crystal Polymer) |
| Dimensions | |
| Connector Height | 3.05 mm[.12 in] |
| Stack Height | 5 mm, 8 mm, 11 mm, 16 mm, 19 mm, 22 mm, 25 mm, 30 mm[1.181 in] |
| PCB Thickness (Recommended) | .05 mm[.12 in] |
| Usage Conditions | |
| Operating Temperature Range | -65 – 125 °C[-85 – 257 °F] |
| | |



Operation/Application

| Assembly Process Feature | Pick and Place Cover |
|--------------------------|----------------------|
| Circuit Application | Power & Signal |
| Industry Standards | |
| UL Flammability Rating | UL 94V-0 |
| Packaging Features | |
| Packaging Quantity | 42 |
| Packaging Type | Box, Tray |

Product Compliance

For compliance documentation, visit the product page on TE.com>

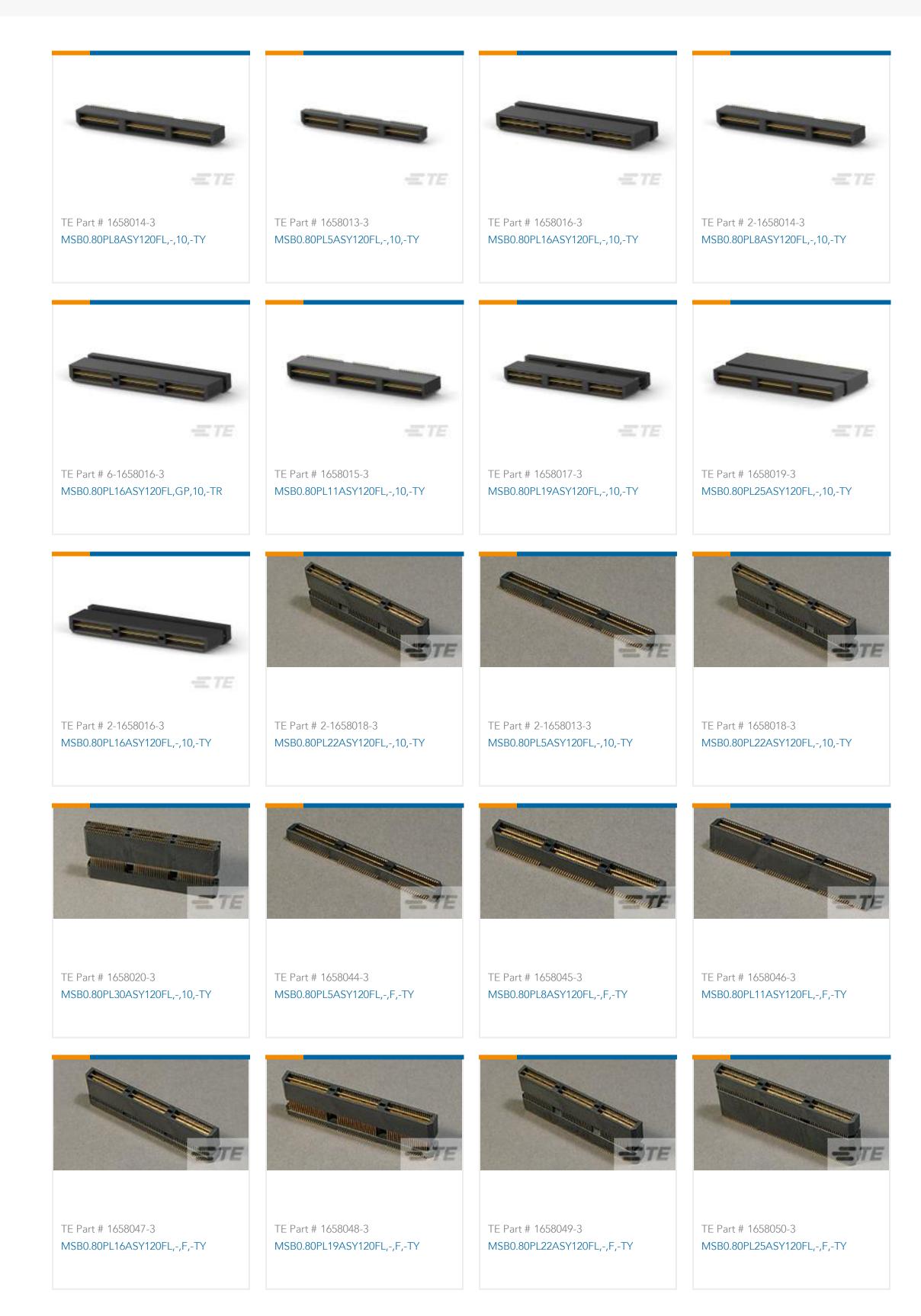
| EU RoHS Directive 2011/65/EU | Compliant |
|---|--|
| EU ELV Directive 2000/53/EC | Compliant |
| China RoHS 2 Directive MIIT Order No 32, 2016 | No Restricted Materials Above Threshold |
| EU REACH Regulation (EC) No. 1907/2006 | Current ECHA Candidate List: JUNE 2023 (235) Candidate List Declared Against: JAN 2023 (233) Does not contain REACH SVHC |
| Halogen Content | Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free |
| Solder Process Capability | Reflow solder capable to 260°C |

Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-on-reach

Compatible Parts





Customers Also Bought

















Documents

Product Drawings

MSB0.80RC-ASY120FL,-,F,-TY

English

CAD Files

3D PDF

3D

Customer View Model

ENG_CVM_CVM_2-1658043-3_L.2d_dxf.zip

English

Customer View Model

ENG_CVM_CVM_2-1658043-3_L.3d_igs.zip

English

Customer View Model

ENG_CVM_CVM_2-1658043-3_L.3d_stp.zip

English

By downloading the CAD file I accept and agree to the **Terms and Conditions** of use.

Datasheets & Catalog Pages

MICTOR SB Interconnection System

English

Product Specifications

Application Specification

English